

## 20V Dual N-Channel Enhancement Mode MOSFET

Dual N-Channel Enhancement Mode

### DESCRIPTION

The STN8205 is the Dual N-Channel logic enhancement mode power field effect transistor which is produced using high cell density, advanced trench technology to provide excellent  $R_{DS(ON)}$ .

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, and low in-line power loss are needed in a very small outline surface mount package.

### FEATURE

- ◆ **20V / 6.0A,  $R_{DS(ON)} = 21m\Omega(typ.)@V_{GS} = 4.5V$**
- ◆ **20V / 5.2A,  $R_{DS(ON)} = 25m\Omega(typ.)@V_{GS} = 2.5V$**
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Exceptional on-resistance and Maximum DC current capability
- ◆ This is a Full RoHS compliance
- ◆ TSSOP-8 package design

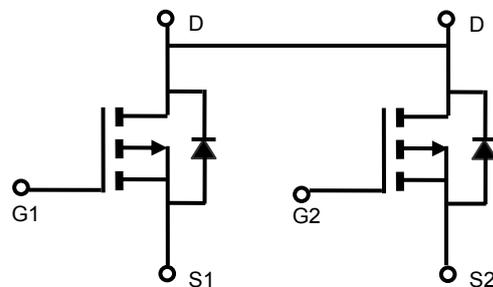
### APPLICATIONS

- ◆ Power Management in Note book
- ◆ Portable Equipment
- ◆ Battery Powered System

### PIN CONFIGURATION



TOP VIEW  
TSSOP-8



Dual N-Channle

### PART NUMBER INFORMATION

<p>STN8205X- XX X</p> <p>└───┬───┬───┘</p> <p>    └───┘</p> <p>    └───┘</p> <p>    └───┘</p> <p>          Lead Plating Code</p> <p>          Handling Code</p> <p>          Package Code</p>	<p><b>Lead Plating Code</b></p> <p>G : Halogen &amp; Lead-free product. This product is RoHS compliant</p> <p><b>Handling Code</b></p> <p>TR : Tape&amp;Reel</p> <p><b>Package Code</b></p> <p>W : TSSOP-8</p>
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**ORDERING INFORMATION**

Part Number	Package Code	Package	Shipping
STN8205W-TRG	W	TSSOP-8	3000 / Tape&Reel

※ Year Code : 0 ~ 9

※ Week Code : A ~ Z(1~26) ; a ~ z(27~52)

※ G : Lead-free product. This product is RoHS compliant.

**ABSOLUTE MAXIMUM RATINGS** ( $T_A = 25^\circ\text{C}$  Unless otherwise noted )

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current ( $T_J=150^\circ\text{C}$ )	$V_{GS}=4.5\text{V}$ 6	A
$I_{DM}$	Pulsed Drain Current	20	A
$I_S$	Continuous Source Current (Diode Conduction)	1	A
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$ $T_A=70^\circ\text{C}$ 1.5 0.9	W
$T_J$	Operation Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ\text{C}$

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

**THERMAL DATA**

Symbol	Parameter	Min	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		62.5		$^\circ\text{C}/\text{W}$

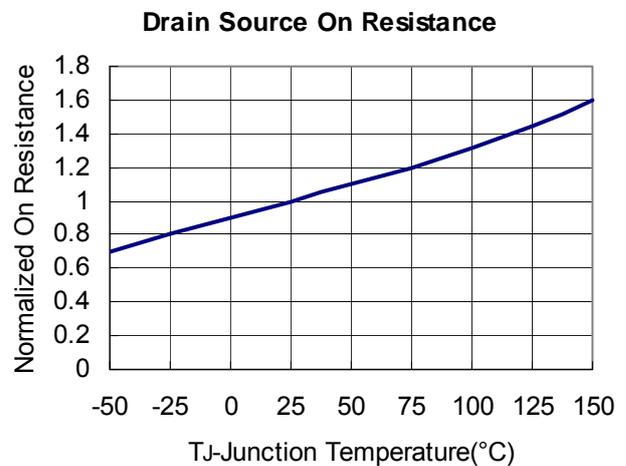
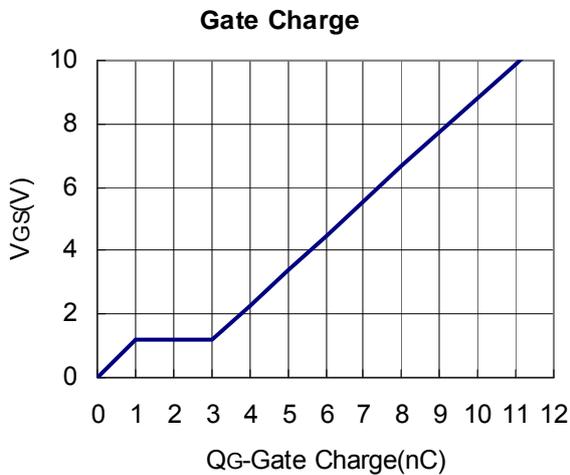
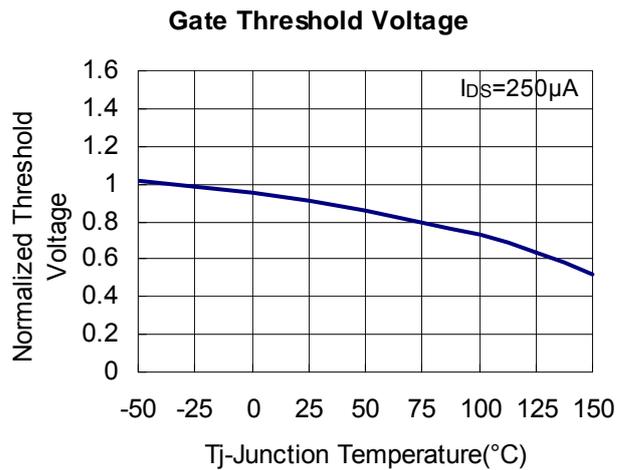
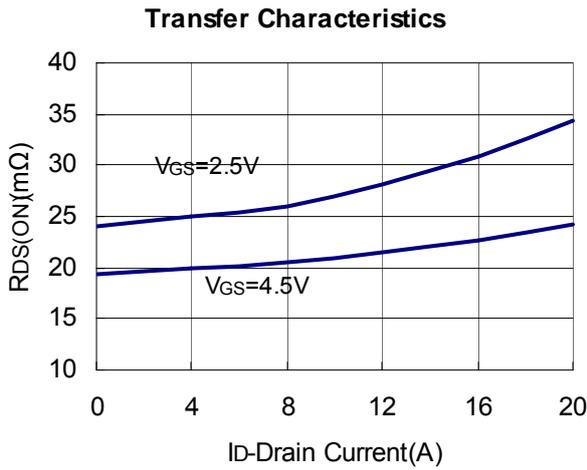
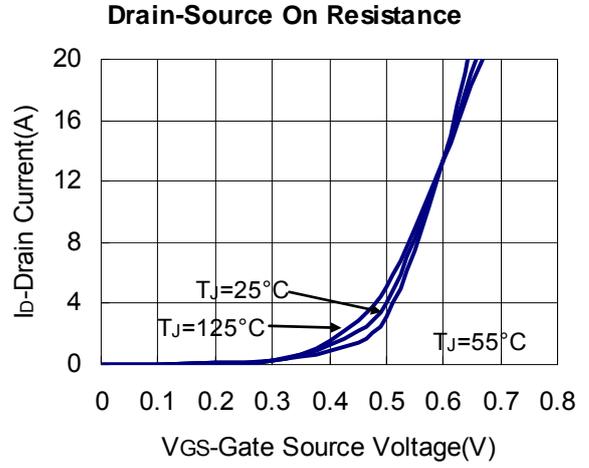
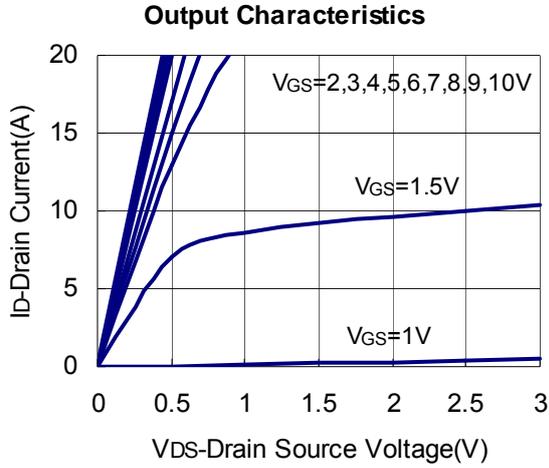
**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5		1.0	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=16V, V_{GS}=0V$			1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			30	
$I_{D(ON)}$	On-State Drain Current	$V_{DS} \geq 5V, V_{GS}=4.5V$	6			A
$R_{DS(ON)}$	Drain-source On-Resistance	$V_{GS}=4.5V, I_D=6.0A$ $V_{GS}=2.5V, I_D=5.2A$		21 25	26 32	m $\Omega$
$G_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=3.6A$		10		S
<b>Source-Drain Diode</b>						
$V_{SD}$	Diode Forward Voltage	$I_S=1.7A, V_{GS}=0V$		0.8	1.3	V
<b>Dynamic Parameters</b>						
$Q_g$	Total Gate Charge	$V_{DS}=10V$ $V_{GS}=4.5V$ $I_D=6A$		21	29	nC
$Q_{gs}$	Gate-Source Charge			1.3		
$Q_{gd}$	Gate-Drain Charge			3.3		
$C_{iss}$	Input Capacitance	$V_{DS}=10V$ $V_{GS}=0V$ $f=1\text{MHz}$		595		pF
$C_{oss}$	Output Capacitance			140		
$C_{riss}$	Reverse Transfer Capacitance			125		
$t_{d(on)}$	Turn-On Time	$V_{DD}=10V$ $R_L=10\Omega$ $I_D=1.0A$ $V_{GEN}=4.5V$ $R_G=6\Omega$		3.5	7	nS
$t_r$				13.5	25	
$t_{d(off)}$	Turn-Off Time			32	58	
$T_f$				6.6	13	

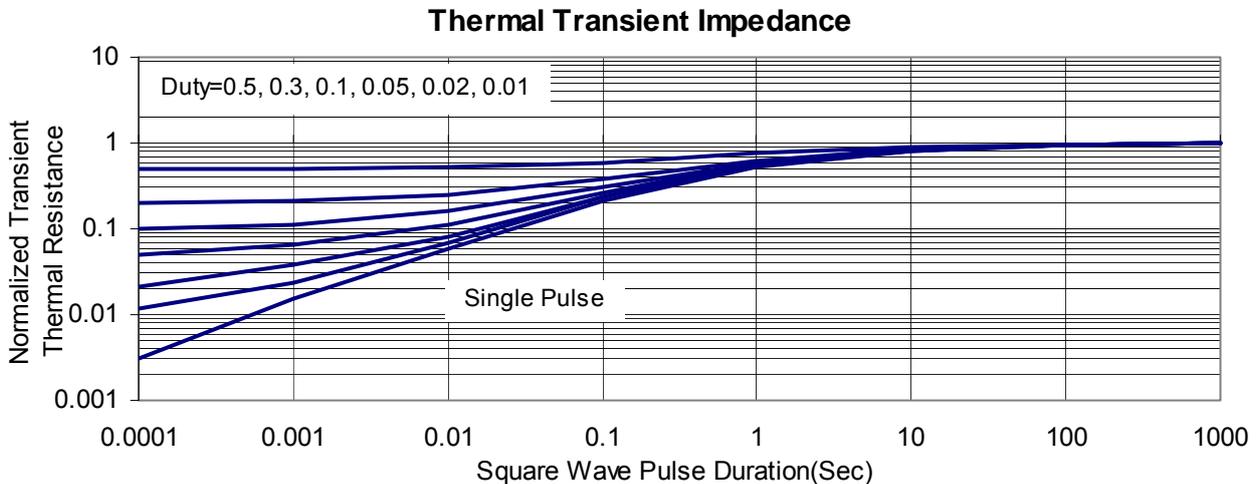
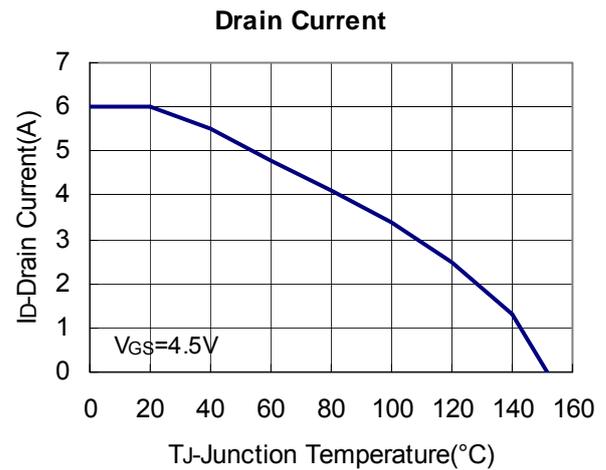
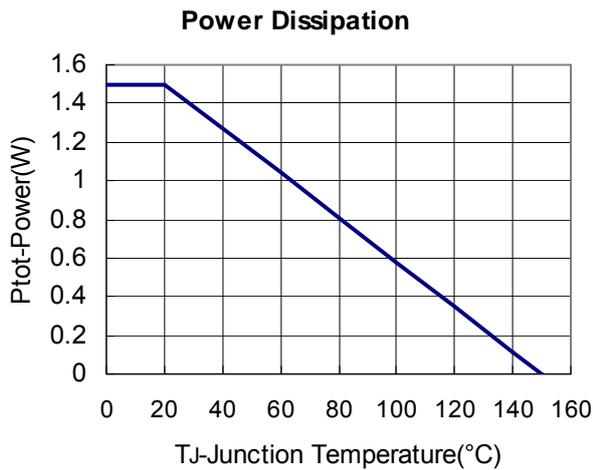
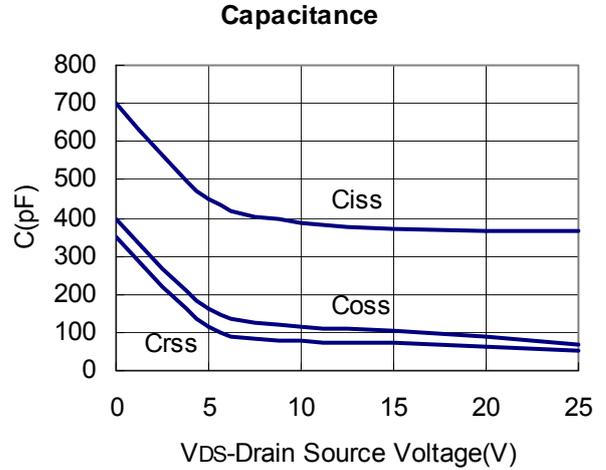
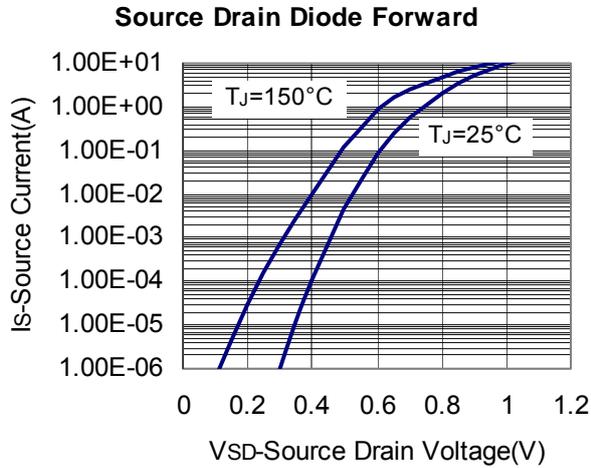
 Note : 1. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ 

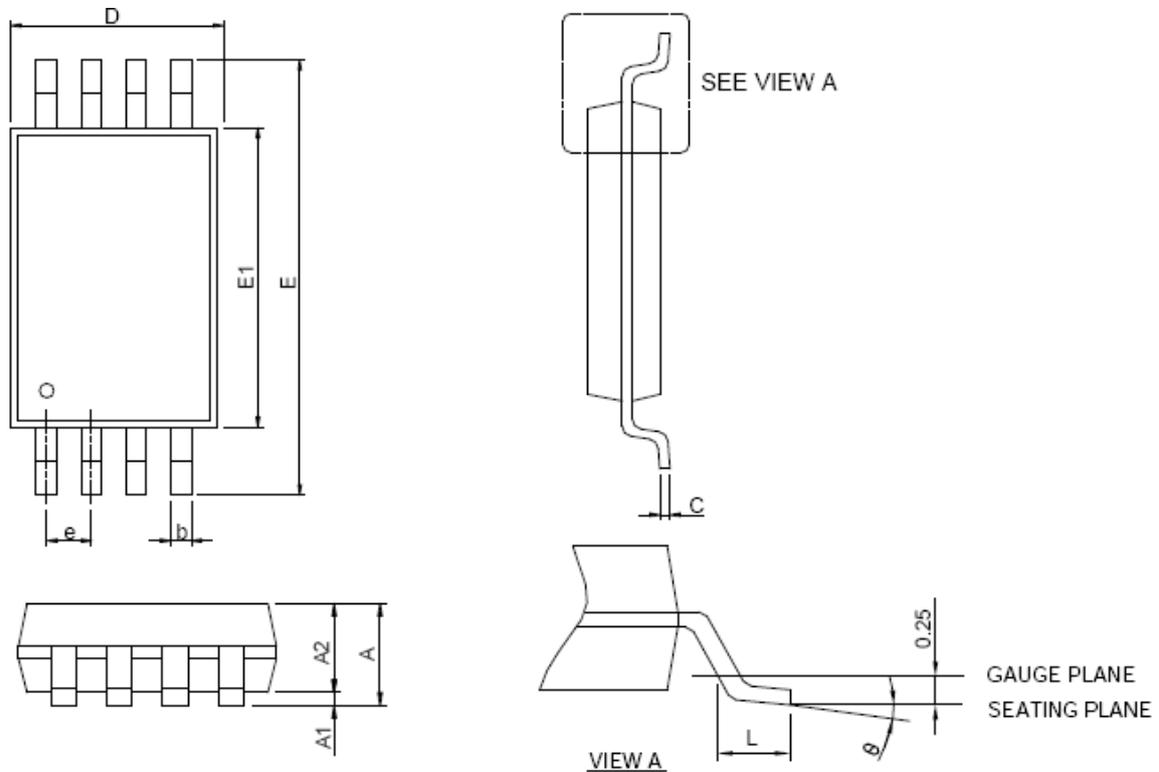
2. Static parameters are based on package level with recommended wire-bonding

■ TYPICAL CHARACTERISTICS (25°C Unless Note)



■ TYPICAL CHARACTERISTICS (25°C Unless Note)



**TSSOP-8 PACKAGE DIMENSIONS**


SYMBOL	TSSOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.20		0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.031	0.041
b	0.19	0.30	0.007	0.012
c	0.09	0.20	0.004	0.008
D	2.90	3.10	0.114	0.122
E	6.20	6.60	0.244	0.260
E1	4.30	4.50	0.169	0.177
e	0.65 BSC		0.026 BSC	
L	0.45	0.75	0.018	0.030
θ	0°	8°	0°	8°